

**IN THE CLAIMS**

1. (original) A frame attaching process adapted to attach an attaching surface of a transparent substrate to an active area of a chip by a frame, the active area of the chip comprising a functional area, the frame attaching process comprising:

forming the frame on the active area of the chip, the frame surrounding the functional area;

attaching the attaching surface of the transparent substrate to the frame formed on the active area of the chip under a negative pressure; and

solidifying the frame.

2. (original) The frame attaching process of claim 1, wherein the negative pressure ranges from about 0.5 to about 0.9 atmospheres.

3. (original) The frame attaching process of claim 1, wherein the step of solidifying the frame is performed by exposing the frame to an ultraviolet light.

4. (withdrawn) A frame attaching process adapted to attach an attaching surface of a transparent substrate to an active area of a chip using a frame, the active area of the chip comprising a functional area, the frame attaching process comprising:

forming the frame on the attaching surface of the transparent substrate;

attaching the frame formed on the attaching surface of the transparent substrate to the active area of the chip under a negative pressure, the frame surrounding the functional area; and

solidifying the frame.

5. (withdrawn) The frame attaching process of claim 4, wherein the negative pressure ranges from about 0.5 to about 0.9 atmospheres.

6. (withdrawn) The frame attaching process of claim 4, wherein the step of solidifying the frame is performed by exposing the frame to an ultraviolet light.

7. (original) A frame attaching process adapted to attach an attaching surface of a transparent substrate to an active area of a chip using a frame, the active area of the chip

comprising a functional area, the frame attaching process comprising:

attaching the attaching surface of the transparent substrate to the active area of the chip using the frame under a negative pressure, the frame surrounding the functional area; and  
solidifying the frame.

8. (original) The frame attaching process of claim 7, further comprising forming the frame on the active area of the chip before the step of attaching the transparent substrate to the active area of the chip.

9. (withdrawn) The frame attaching process of claim 7, further comprising forming the frame on the attaching surface of the transparent substrate before the step of attaching the transparent substrate to the active area of the chip.

10. (original) The frame attaching process of claim 7, wherein the negative pressure ranges from about 0.5 to about 0.9 atmospheres.

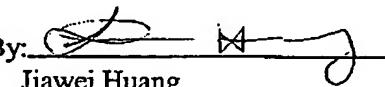
11. (original) The frame attaching process of claim 7, wherein the step of solidifying the frame is performed by exposing the frame to an ultraviolet light.

No new matter adds through the above amendment. Entry of the amendment is requested.

No fee is believed to be due in connection with the filing of this paper. However, the Commissioner is authorized to charge any fees that may be required to Account No. 50-0710 (Order No. JCLA12114).

Respectfully submitted,  
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